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ABSTRACT OF THE DISCLOSURE

A plastic ball grid array package is designed to pass the JEDEC Level 1 Moisture Sensitivity Test (the "popcorn test"). The plastic ball grid array design minimizes contact between a mold compound/encapsulate/glob top and metal surfaces. The present plastic ball grid array design maximizes contact between the mold compound/encapsulate/glob top and either the laminate core or the solder resist in order to take advantage of this strong bond which will help disable delamination. Furthermore, solder resistive material overlaps the interface between metal surfaces and the laminate core.

(Fig. 4)

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